# **General Purpose Transistors**

#### **NPN Silicon**

#### **Features**

• Pb-Free Packages are Available\*

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V <sub>CEO</sub>	40	Vdc
Collector - Base Voltage	V <sub>CBO</sub>	60	Vdc
Emitter - Base Voltage	V <sub>EBO</sub>	6.0	Vdc
Collector Current – Continuous	Ic	600	mAdc
Total Device Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	625 5.0	mW mW/°C
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	1.5 12	W mW/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

#### THERMAL CHARACTERISTICS

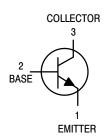
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	83.3	°C/W

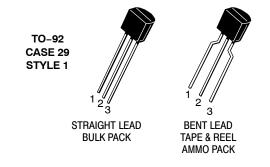
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



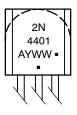
#### ON Semiconductor®

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#### **MARKING DIAGRAM**



2N4401 = Device Code A = Assembly Location

Y = Year WW = Work Week ■ = Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

1

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

	Characte	ristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				•	•	•
Collector-Emitter Breakdow	n Voltage (Note 1	) $(I_C = 1.0 \text{ mAdc}, I_B = 0)$	V <sub>(BR)CEO</sub>	40	-	Vdc
Collector-Base Breakdown	Voltage	$(I_C = 0.1 \text{ mAdc}, I_E = 0)$	V <sub>(BR)CBO</sub>	60	-	Vdc
Emitter-Base Breakdown V	oltage	(I <sub>E</sub> = 0.1 mAdc, I <sub>C</sub> = 0)	V <sub>(BR)EBO</sub>	6.0	-	Vdc
Base Cutoff Current		(V <sub>CE</sub> = 35 Vdc, V <sub>EB</sub> = 0.4 Vdc)	I <sub>BEV</sub>	-	0.1	μAdc
Collector Cutoff Current		(V <sub>CE</sub> = 35 Vdc, V <sub>EB</sub> = 0.4 Vdc)	I <sub>CEX</sub>	-	0.1	μAdc
ON CHARACTERISTICS (N	lote 1)					
DC Current Gain		$ \begin{array}{l} (I_{C}=0.1 \text{ mAdc, } V_{CE}=1.0 \text{ Vdc}) \\ (I_{C}=1.0 \text{ mAdc, } V_{CE}=1.0 \text{ Vdc}) \\ (I_{C}=10 \text{ mAdc, } V_{CE}=1.0 \text{ Vdc}) \\ (I_{C}=150 \text{ mAdc, } V_{CE}=1.0 \text{ Vdc}) \\ (I_{C}=500 \text{ mAdc, } V_{CE}=2.0 \text{ Vdc}) \end{array} $	h <sub>FE</sub>	20 40 80 100 40	- - 300 -	-
Collector - Emitter Saturation	n Voltage	$(I_C = 150 \text{ mAdc}, I_B = 15 \text{ mAdc})$ $(I_C = 500 \text{ mAdc}, I_B = 50 \text{ mAdc})$	V <sub>CE(sat)</sub>	- -	0.4 0.75	Vdc
Base - Emitter Saturation Vo	ltage	$(I_C = 150 \text{ mAdc}, I_B = 15 \text{ mAdc})$ $(I_C = 500 \text{ mAdc}, I_B = 50 \text{ mAdc})$	V <sub>BE(sat)</sub>	0.75 -	0.95 1.2	Vdc
SMALL-SIGNAL CHARAC	TERISTICS					
Current-Gain - Bandwidth	Product (I	C = 20 mAdc, V <sub>CE</sub> = 10 Vdc, f = 100 MHz)	f <sub>T</sub>	250	_	MHz
Collector-Base Capacitance	)	(V <sub>CB</sub> = 5.0 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)	C <sub>cb</sub>	-	6.5	pF
Emitter-Base Capacitance		(V <sub>EB</sub> = 0.5 Vdc, I <sub>C</sub> = 0, f = 1.0 MHz)	C <sub>eb</sub>	-	30	pF
Input Impedance	(	I <sub>C</sub> = 1.0 mAdc, V <sub>CE</sub> = 10 Vdc, f = 1.0 kHz)	h <sub>ie</sub>	1.0	15	kΩ
Voltage Feedback Ratio	(	$I_C = 1.0 \text{ mAdc}, V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz})$	h <sub>re</sub>	0.1	8.0	X 10 <sup>-4</sup>
Small-Signal Current Gain	(	I <sub>C</sub> = 1.0 mAdc, V <sub>CE</sub> = 10 Vdc, f = 1.0 kHz)	h <sub>fe</sub>	40	500	-
Output Admittance	(	I <sub>C</sub> = 1.0 mAdc, V <sub>CE</sub> = 10 Vdc, f = 1.0 kHz)	h <sub>oe</sub>	1.0	30	μmhos
SWITCHING CHARACTER	ISTICS					
Delay Time (V <sub>CC</sub> = 30 Vdc, V <sub>BE</sub> = 2.0 Vdc,		t <sub>d</sub>	_	15	ns	
Rise Time	$I_C$ = 150 mAdc, I	<sub>B1</sub> = 15 mAdc)	t <sub>r</sub>	-	20	ns
Storage Time	(V <sub>CC</sub> = 30 Vdc, I	C = 150 mAdc,	t <sub>s</sub>	-	225	ns
Fall Time	$I_{B1} = I_{B2} = 15 \text{ m/}$	Adc)	t <sub>f</sub>	-	30	ns

<sup>1.</sup> Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2.0%.

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
2N4401	TO-92	5000 Units / Bulk
2N4401G	TO-92 5000 Units / Bulk (Pb-Free)	
2N4401RLRA	TO-92	2000 / Tape & Reel
2N4401RLRAG	TO-92 (Pb-Free)	2000 / Tape & Reel
2N4401RLRMG	TO-92 (Pb-Free)	2000 / Tape & Ammo Box
2N4401RLRP	TO-92	2000 / Tape & Ammo Box
2N4401RLRPG	TO-92 (Pb-Free)	2000 / Tape & Ammo Box

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### **SWITCHING TIME EQUIVALENT TEST CIRCUITS**

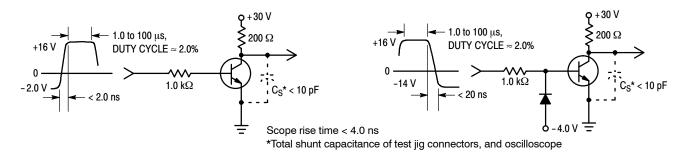


Figure 1. Turn-On Time

Figure 2. Turn-Off Time

#### TRANSIENT CHARACTERISTICS

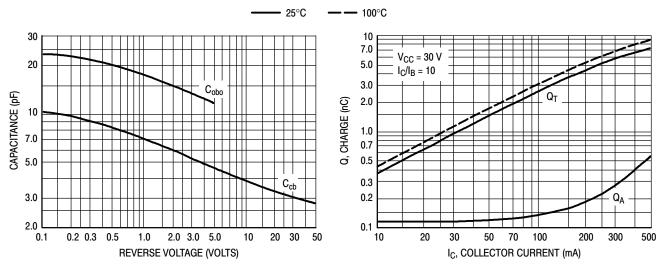


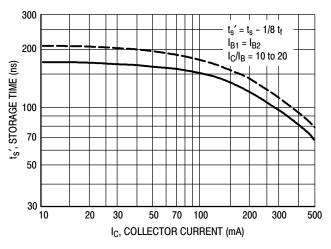
Figure 3. Capacitances

100 100  $I_C/I_B = 10$  $V_{CC} = 30 \text{ V}$ 70 70  $I_C/I_B = 10$ 50 50  $t_r @ V_{CC} = 30 V$ t, TIME (ns) 30 t<sub>r</sub> @ V<sub>CC</sub> = 10 V 30 t, TIME (ns)  $t_{d} @ V_{EB} = 2.0 V$ 20 20  $t_{d} @ V_{EB} = 0$ 10 10 7.0 7.0 5.0 5.0 10 70 100 200 20 300 500 10 20 70 100 500 IC, COLLECTOR CURRENT (mA) IC, COLLECTOR CURRENT (mA)

Figure 5. Turn-On Time

Figure 6. Rise and Fall Times

Figure 4. Charge Data



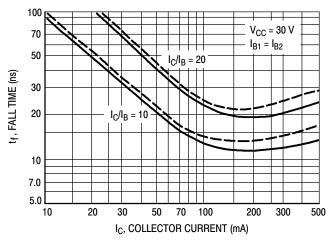
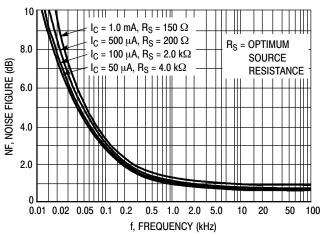


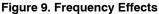
Figure 7. Storage Time

Figure 8. Fall Time

## SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE

 $V_{CE}$  = 10 Vdc,  $T_A$  = 25°C; Bandwidth = 1.0 Hz





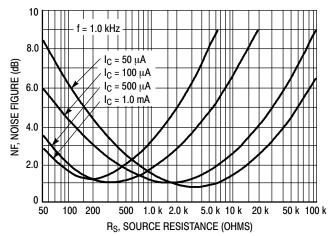


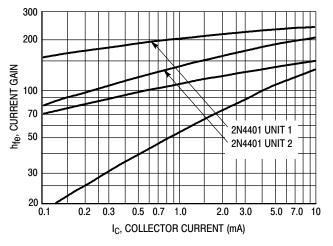
Figure 10. Source Resistance Effects

#### **h PARAMETERS**

 $V_{CE}$  = 10 Vdc, f = 1.0 kHz,  $T_A$  = 25°C

This group of graphs illustrates the relationship between h<sub>fe</sub> and other "h" parameters for this series of transistors. To obtain these curves, a high-gain and a low-gain unit were

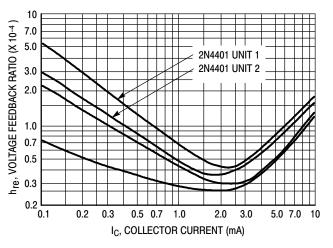
selected from the 2N4401 lines, and the same units were used to develop the correspondingly numbered curves on each graph.



50 k 2N4401 UNIT 1 2N4401 UNIT 2 h<sub>ie</sub>, INPUT IMPEDANCE (OHMS) 20 k 10 k 5.0 k 2.0 k 1.0 k 500 0.2 0.5 0.7 1.0 2.0 7.0 10 IC, COLLECTOR CURRENT (mA)

Figure 11. Current Gain

Figure 12. Input Impedance



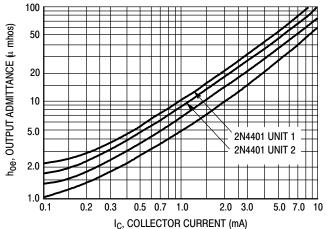


Figure 13. Voltage Feedback Ratio

Figure 14. Output Admittance

#### STATIC CHARACTERISTICS

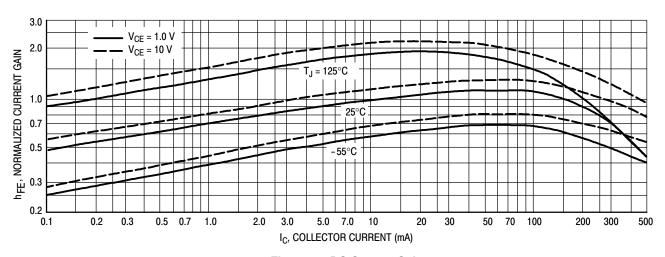


Figure 15. DC Current Gain

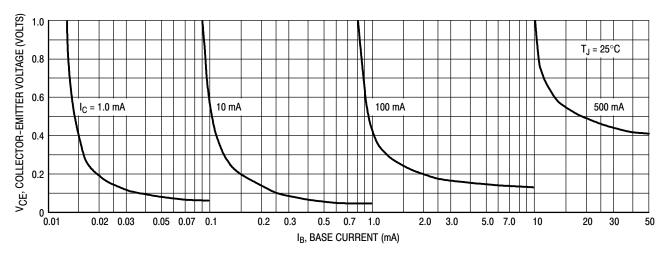


Figure 16. Collector Saturation Region

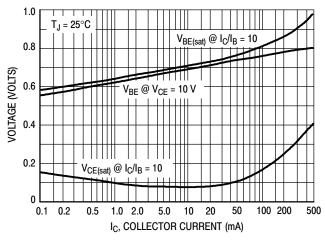


Figure 17. "On" Voltages

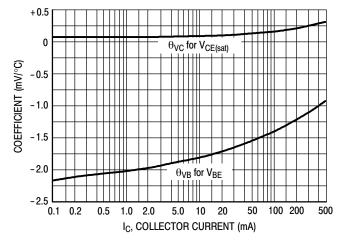
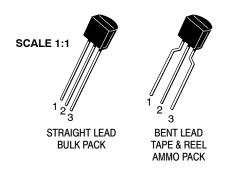
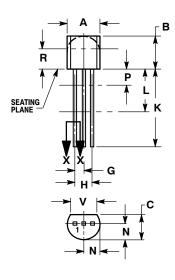


Figure 18. Temperature Coefficients



**TO-92 (TO-226)** CASE 29-11 **ISSUE AM** 

**DATE 09 MAR 2007** 

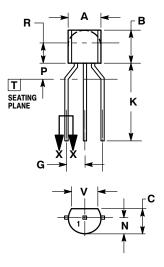


STRAIGHT LEAD **BULK PACK** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
  4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500		12.70	
L	0.250		6.35	
N	0.080	0.105	2.04	2.66
Р		0.100		2.54
R	0.115		2.93	
٧	0.135		3.43	



**BENT LEAD** TAPE & REEL AMMO PACK



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
  4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	MILLIMETERS				
DIM	MIN	MAX			
Α	4.45	5.20			
В	4.32	5.33			
С	3.18	4.19			
D	0.40	0.54			
G	2.40	2.80			
J	0.39	0.50			
K	12.70				
N	2.04	2.66			
P	1.50	4.00			
R	2.93				
V	3.43				

#### **STYLES ON PAGE 2**

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## **TO-92 (TO-226)** CASE 29-11

### ISSUE AM

#### DATE 09 MAR 2007

STYLE 1: PIN 1. 2. 3.	EMITTER BASE COLLECTOR	STYLE 2: PIN 1. 2. 3.	BASE EMITTER COLLECTOR	STYLE 3: PIN 1. 2. 3.	ANODE ANODE CATHODE	STYLE 4: PIN 1. 2. 3.	CATHODE CATHODE ANODE	STYLE 5: PIN 1. 2. 3.	DRAIN
2.	GATE SOURCE & SUBSTRATE DRAIN	STYLE 7: PIN 1. 2. 3.	SOURCE DRAIN GATE	STYLE 8: PIN 1. 2. 3.	DRAIN GATE SOURCE & SUBSTRATE	PIN 1.	BASE 1		CATHODE
2.	ANODE CATHODE & ANODE CATHODE	STYLE 12: PIN 1. 2. 3.	MAIN TERMINAL 1 GATE MAIN TERMINAL 2	PIN 1.	ANODE 1	PIN 1.	EMITTER COLLECTOR BASE	PIN 1. 2.	
2.	ANODE GATE	PIN 1. 2.	COLLECTOR BASE	PIN 1. 2.	ANODE CATHODE	PIN 1. 2.	GATE	2.	NOT CONNECTED
2.	COLLECTOR	PIN 1. 2.	SOURCE GATE DRAIN	STYLE 23: PIN 1. 2. 3.	GATE SOURCE DRAIN	STYLE 24: PIN 1. 2. 3.	EMITTER COLLECTOR/ANODE CATHODE	STYLE 25: PIN 1. 2. 3.	MT 1 GATE
	V <sub>CC</sub>	PIN 1. 2.	MT	STYLE 28: PIN 1. 2.	CATHODE ANODE GATE	STYLE 29: PIN 1. 2.		PIN 1. 2.	DRAIN
	GATE	PIN 1. 2.		STYLE 33: PIN 1. 2. 3.	RETURN	2.			

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